

ADXL343 Wiring

Size: A

Number: 1

Revision: 0.1

Date: 10/30/2021

Time: 11:05:56 PM

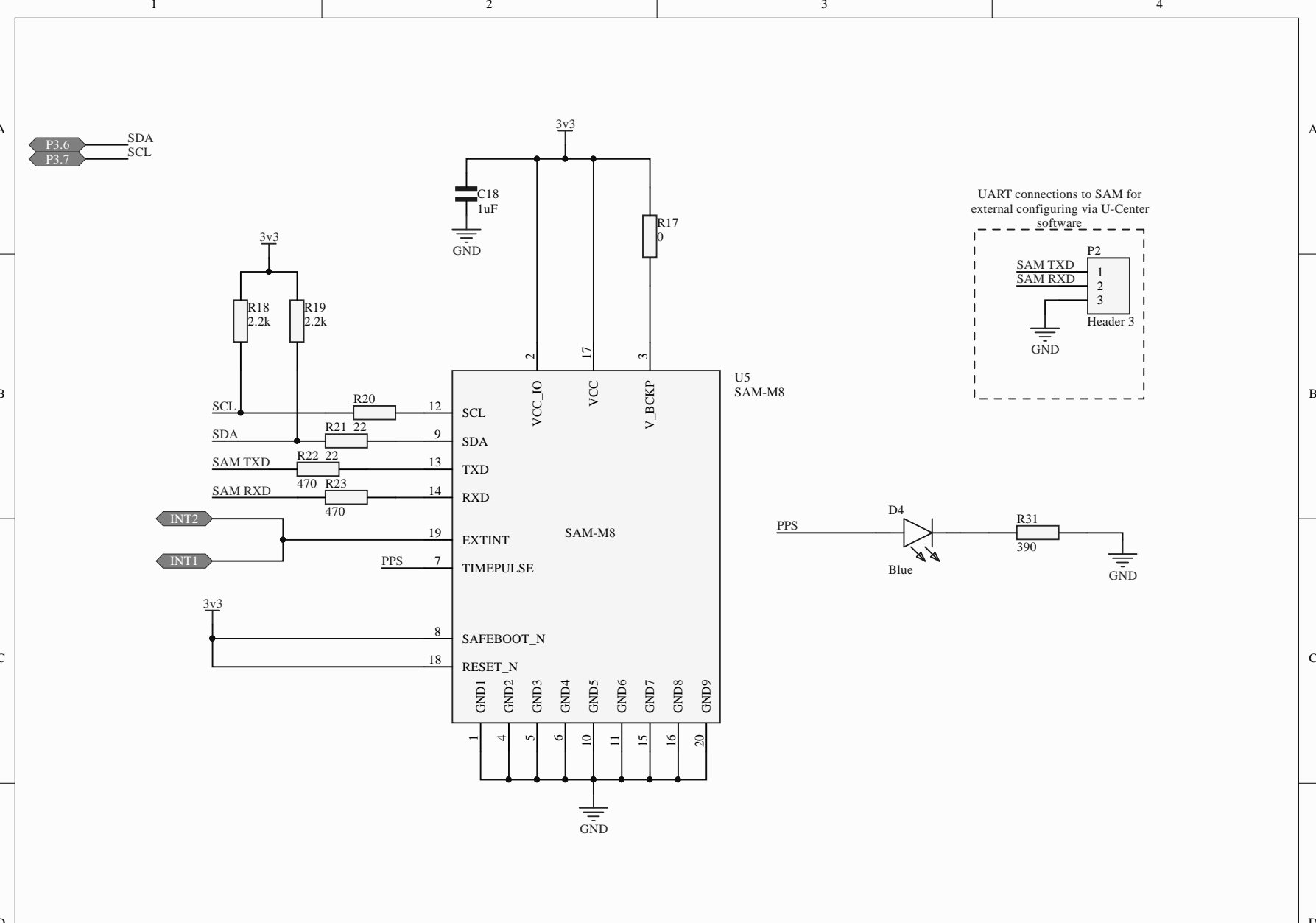
Sheet 3 of 7

Kennedy Hall of Engineering
301 Fulton St. W
Grand Rapids, MI 49504

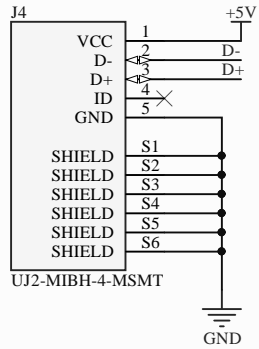
Engineer: Jesse Fernandez

File: W:\Altium\436-Final-Project-main\436-Final-Project-main\Altium\GPS_Tracker_Logger\PCB\PCB_CAD\PCB_CAD.dwg

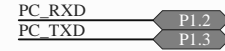




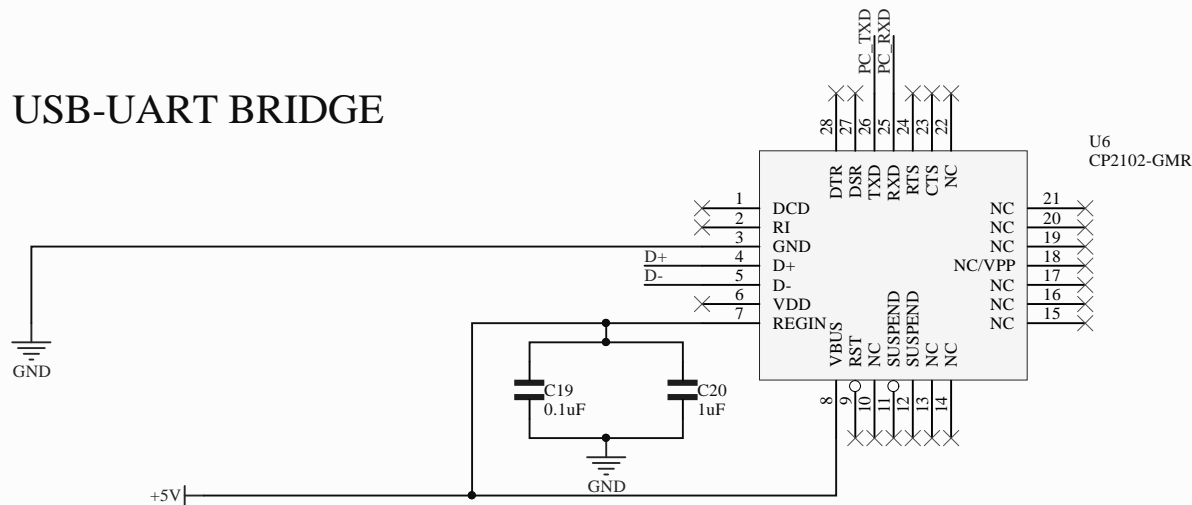
MICRO USB , TYPE B



PC-MSP UART INTERFACE



USB-UART BRIDGE



Title **USB-UART Dongle**

Size: A

Number: 1

Revision: 0.1

Date: 10/30/2021

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Sheet 5 of 7

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Grand Rapids, MI 49504

Engineer: Jesse Fernandez

File: W:\Altium\436-Final-Project-main\436-Final-Project-main\Altium\GPS_Tracker_Logger\USB-UART-Interface\PC-MSP UART Interface.Doc



A

B

C

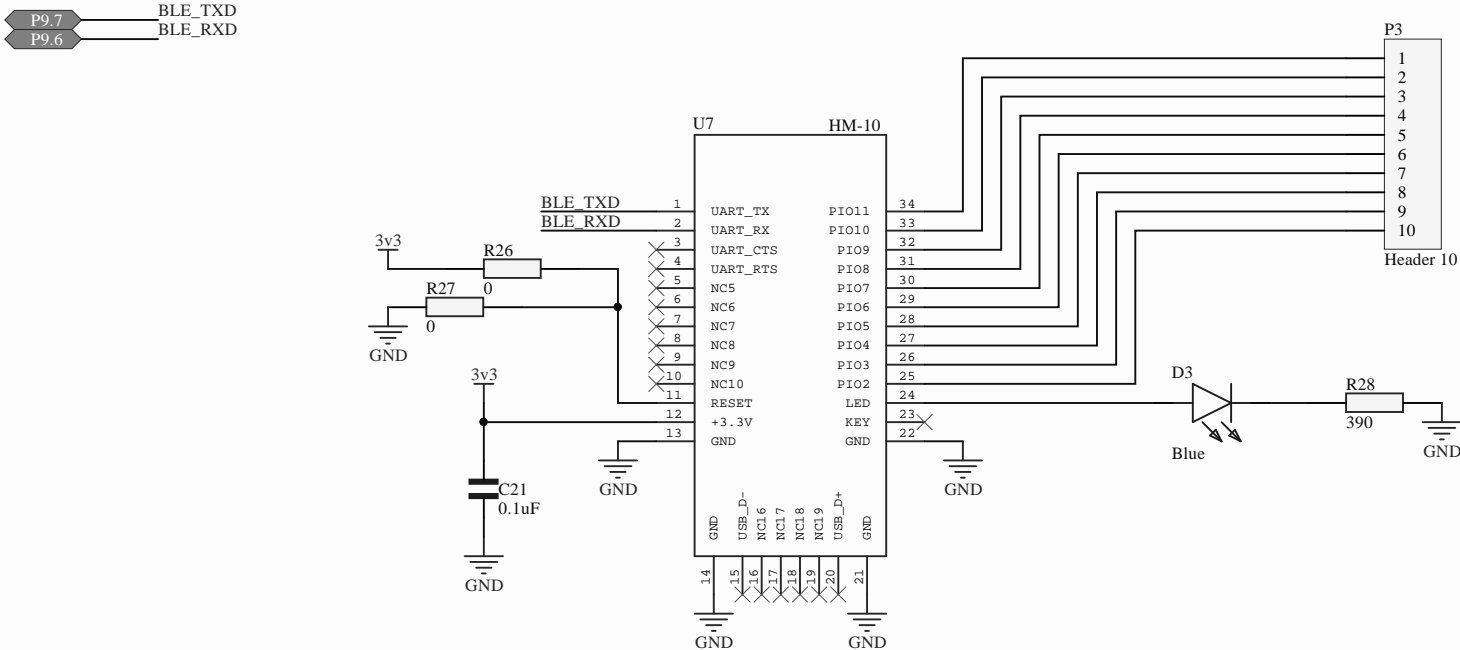
D


A

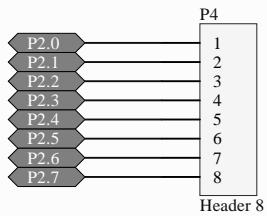
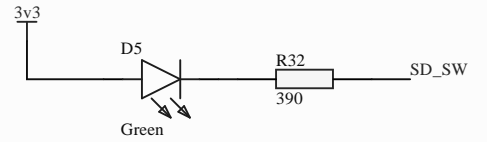
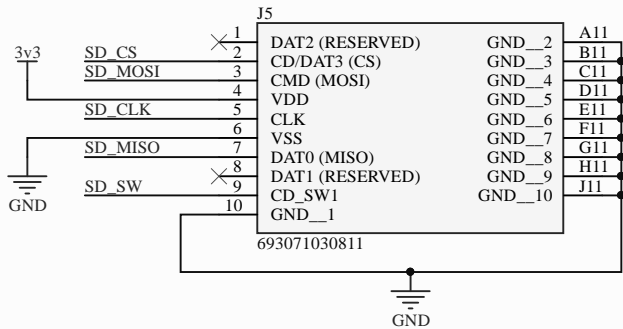
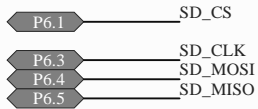
B


C

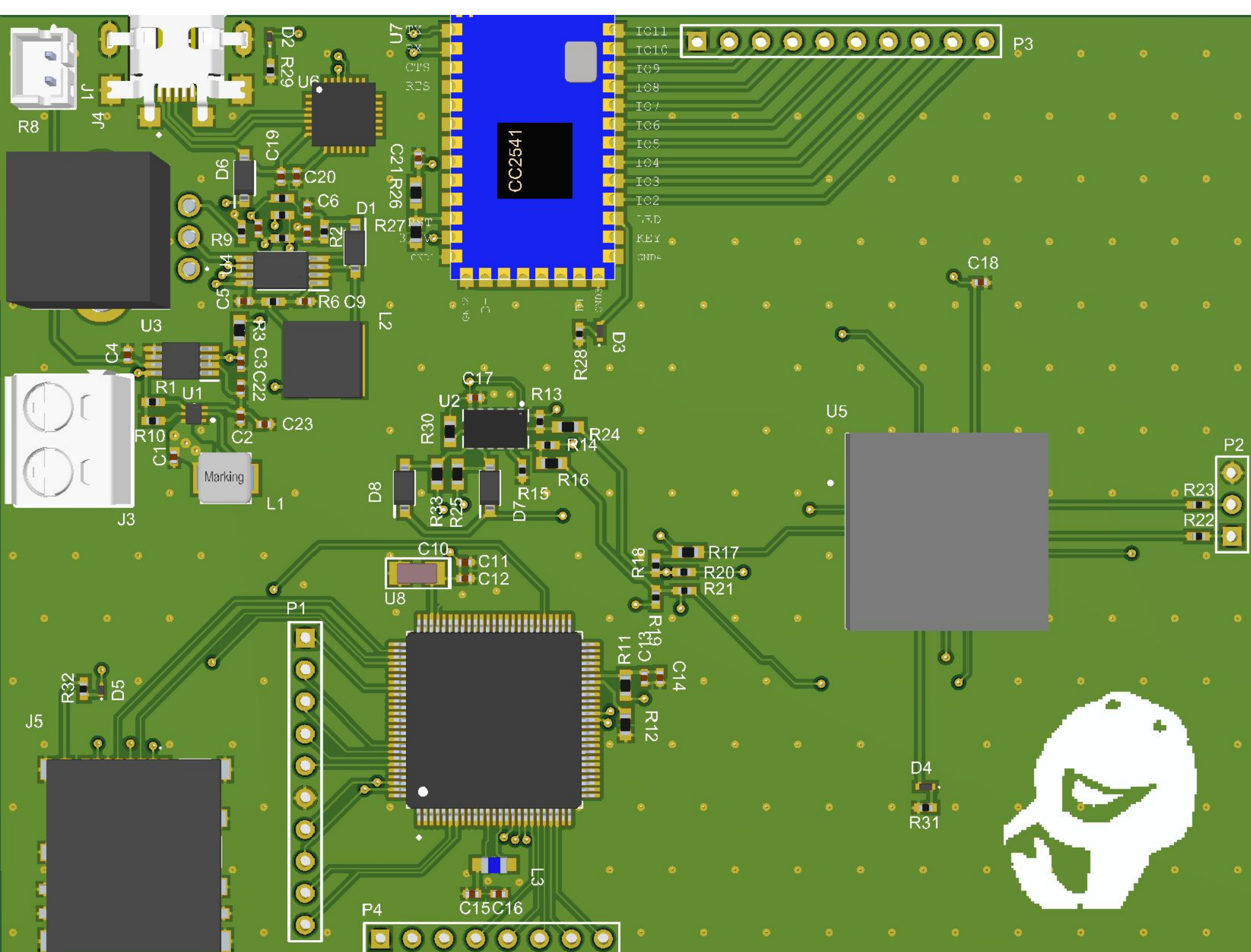
D



Title HM-10 (BLE) Wiring			Kennedy Hall of Engineering 301 Fulton St. W Grand Rapids, MI 49504	 GRAND VALLEY STATE UNIVERSITY 1800 PO. BOX 30000 GRAND RAPIDS, MI 49503-0000
Size: A	Number: 1	Revision: 0.1		
Date: 10/30/2021	Time: 11:05:57 PM	Sheet: 6 of 7	Engineer: Jesse Fernandez	
File: W:\Altium\436-Final-Project-main\436-Final-Project-main\Altium\GPS_Tracker_Logger\HM-10.schDoc			10/30/2021	



Title <i>SD Card Wiring</i>			Kennedy Hall of Engineering 301 Fulton St. W Grand Rapids, MI 49504		 GRAND VALLEY STATE UNIVERSITY SCHOOL OF ENGINEERING
Size: A	Number: 1	Revision 0.1			
Date: 10/30/2021	Time: 11:05:57 PM	Sheet 7 of 7	Engineer: Jesse Fernandez		
File: W:\Altium\436-Final-Project-main\436-Final-Project-main\Altium\GPS_Tracker_Logger\SD_Card_Wiring			Student: [redacted]		

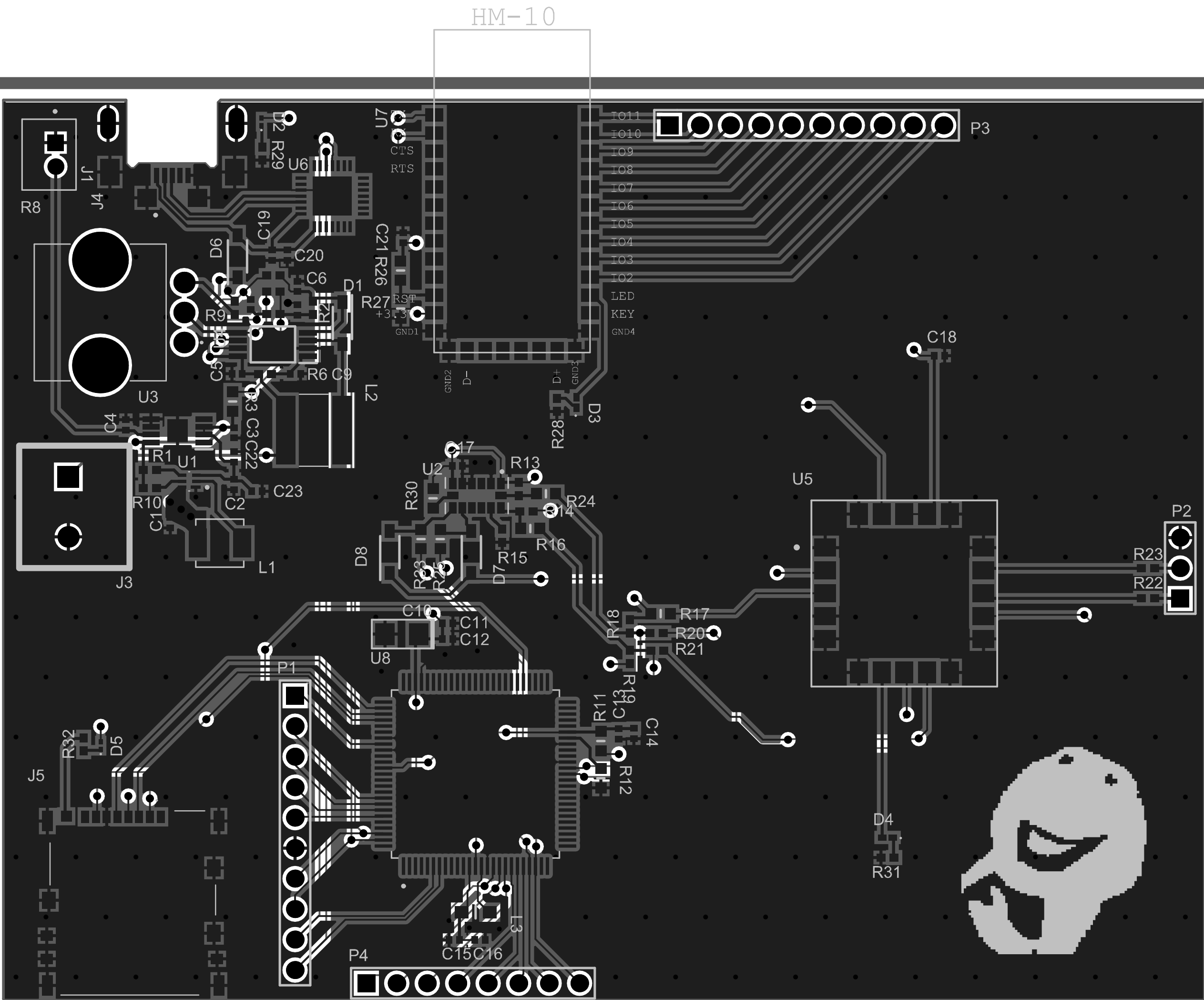


3) RIGID PCB: 4 LAYER
7) BOARD OUTLINE: DEFINED ON GM30. FABRICATION NOTES ON GM30 (AND OVERLaid ON EACH FILE).
3) BOARD THICKNESS: 1.575MM +/- 10%, MEASURED CUT TO CU.
4) BOARD MATERIAL: MULTIFUNCTIONAL FR-4 EPOXY GLASS LAMINATE, ISO1A 370HR OR EQUIVALENT. MEETS OR EXCEEDS IPC-4101 (ENCL / 21)
5) BOARD FINISH: PLATE ALL EXPOSED CONDUCTIVE PATTERN AREAS ELECTROLESS NICKEL IMMERSION GOLD. MINIMUM NI/AU THICKNESSES PER IPC-4552.
6) BOARD CLASS: BOARD SHALL BE FABRICATED TO IPC CLASS 2 PER IPC-6012 RIGID (CURRENT REV.). INSPECTION PER IPC-A-600 2 (CURRENT REV.)
7) BOARD SOLDERMASK: LPI SOLDERMASK OVER BARE COPPER (SMDIC), COLOR: BLACK, BOTH SIDES. PROCESS SHALL CONFORM TO IPC-SM-840, CLASS H.
8) BOARD SILKSCREEN: NON-CONDUCTIVE EPOXY INK, COLOR: WHITE, BOTH SIDES
9) NO COPPER THICKING ALLOWED ON ANY LAYER.
10) BOARD ROW AND TWIST: MEET IPC-TM-650
11) 0.50Z (18UM) CU LAMINATE ON EXTERNAL LAYERS BEFORE PLATING WITH A MIN. OF 1.0OZ (35UM) FINISHED.

FABRICATION NOTES

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	M1 Top	Copper	1.38mil		
	Dielectric 1-2	PP-006	4.33mil	4.29	
2	M2 Plane 1	Copper	1.38mil		
	Dielectric 2-3	FR-4	44.49mil	3.96	
3	M3 Layer 2	Copper	1.38mil		
	Dielectric 3-4	PP-006	4.33mil	4.29	
4	M4 Bottom	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

Total board thickness: 59.46mil



GVSU

FILECopy of GPS_TRACKER_REV11.PcbDoc
CONFIDENTIAL

PROJECT	GPS Tracker & Logger
ID	
DATE	10/30/2021 11:06:05 PM
VARIANT	[No Variations]
ENGINEER	Collin Barnhardt
	Kennedy Hall of Engineering 301 Fulton St. W, Grand Rapids MI
LAYER	Sheet 1 of 1

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